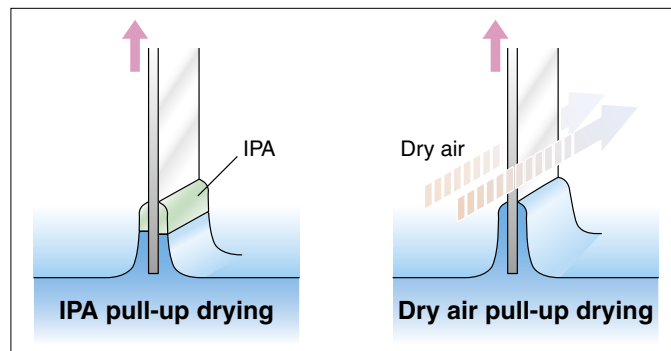


World's first 300-mm semiconductor wafer cleaning equipment with zero VOC emissions developed
— Use of dry air drying technology dramatically reduces running costs and environmental impact —

Dainippon Screen Mfg. Co., Ltd. has recently developed the world's first^{*1} drying technology for use in 300-mm wafer semiconductor device production lines that does not require IPA (isopropyl alcohol). Sales of FC-3100 batch cleaning^{*2} equipment (wet stations) featuring a module known as the Dry-Air Dryer (DAD) that uses this new drying technology will commence in December 2008.



Please download the photo from
<http://www.screen.co.jp/press/nr-photo/indexE.html>

In recent years, the use of ever-finer circuitry has continued to advance in the semiconductor industry. As semiconductor manufacturing processes have become more sophisticated and production volumes have increased, the volume of emissions from chemicals used in various manufacturing processes has also risen. The IPA used in wafer cleaning processes is one of the VOCs (volatile organic compounds) that are regulated under air pollution control laws. Reducing IPA emissions is therefore a major consideration for semiconductor device manufacturers, who are working to reduce their industry's impact on the environment.

The DAD module in the FC-3100 blows ultra-low dew point dry air across wafers, instantly removing any water that remains after cleaning. Since the DAD module uses no IPA, VOC emissions are reduced to zero. Dry air drying not only provides the same performance as conventional drying using IPA, it also cuts processing time in half and can reduce running costs to as little as one-eighth the running costs for conventional drying^{*3}. This method also eliminates the need to install IPA reclamation equipment in factories and use fire prevention equipment, helping to make the FC-3100 both environmentally friendly and safer to operate.

Dainippon Screen will continue to enhance its development of environmentally friendly products as it works to increase its market share in the 300-mm wafer cleaning equipment field, where it already boasts the world's top share, by meeting the market's needs. These efforts will contribute to cementing Screen's position as the global standard for semiconductor cleaning equipment, as well as to the development of the industry.

*1 As of November 2008.

*2 Batch cleaning: A type of processing that makes it possible to clean multiple wafers at the same time.

*3 As compared with conventional Screen equipment.